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Applicant: Salman Akram ✓

§ Group A TECHNOLOGY CENTER 2800
§ 2827

Serial No.: 09/853,111 ✓

§ Examiner: A. Chambliss

Filed: May 10, 2001 ✓

§ Atty. Dkt. No.: MCT.0012D1US
§ (97-0141)For: Method of Fabricating Mounted
Multiple Semiconductor Dies In
A Package (As Amended)Commissioner for Patents
Washington DC 20231

TECHNOLOGY CENTER

d. m.
#10
1/28/03SUPPLEMENTAL RESPONSE

Sir:

In response to the notice of incomplete response, please amend the above-referenced patent application as follows:

Date of Deposit: 01-03-03

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington DC 20231.

Cynthia L. Hayden
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